

## Information Notice number four

Reference: WS2653962508 Plasma Set-up 4 - TiAu RIE

### Introduction

- This Information Notice forms part of the European open Tender procedure with TNO reference number WS2653962508.
- This Information Notice provides a record of the questions submitted by the Tenderers up to and including 15-12-2025 and the answers provided by TNO.
- If Tenderers have asked questions of similar nature, all such questions have nevertheless been included in this Information Notice and answered separately. This may result in repetition of information.
- Where a company name was mentioned in a question, it has been replaced by another word or term to anonymize the questions.
- TNO advises you to read the entire Information Notice.
- All information in the Information Notice is classified as Confidential and may only be used for the purpose of submitting a Tender for this procurement.
- The Information Notice has been made available on TenderNed through publication at [www.tenderned.nl](http://www.tenderned.nl) and added as a document.

The Information Notice serves to provide any additions/changes to the Tender Documents and to communicate announcements from TNO.

Where further clarification of the requirements is provided, this must be taken into account when answering Annex A04 at the time of when compiling the tender. If, for example an alternative is accepted in the Information Notice, Annex A04 will not be revised. The tenderer can answer the question for compliancy with "yes" in both cases (compliancy to the original requirement or compliancy to the alternative). In case a requirement no longer applies, leave the check box in Annex A04 on "select".

Nr	Subject	Question	Answer
1	Annex A04d	Annex A04e R-5000-020 : 1. Do you request a ESC or a mechanical clamping system? 2. With a ESC, we cannot supply 0..100°C temperature control. Is a maximum temperature of 40°C acceptable? With the mechanical clamping system, we can supply the 0..100°C temperature range.	1. An ESC is preferred to prevent risk of damage on the wafers; 2. 40° C is acceptable as long as the rest of the process specifications can be met.